tentative

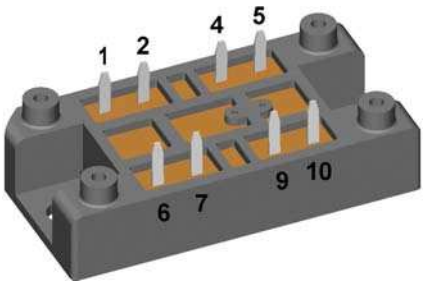
XPT IGBT Module

V_{CES} = 1200V
I_{C25} = 220A
$V_{CE(sat)}$ = 1.8V

Buck Chopper

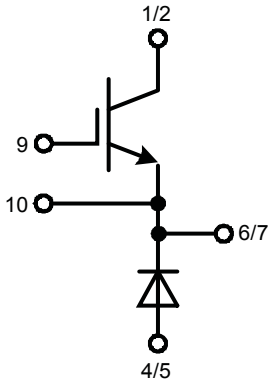
Part number

MIXA150Q1200VA



Backside: isolated

E72873



Features / Advantages:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through) results in:
  - short circuit rated for 10 µsec.
  - very low gate charge
  - low EMI
  - square RBSOA @ 3x Ic
- Thin wafer technology combined with the XPT design results in a competitive low VCE(sat)
- SONIC™ diode
  - fast and soft reverse recovery
  - low operating forward voltage

Applications:

- Switched-mode power supplies
- Switched reluctance motor drive

Package: V1-A-Pack

- Isolation Voltage: 3600V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Height: 17 mm
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

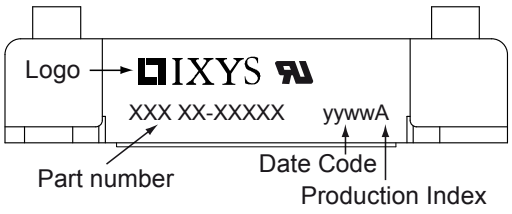
tentative

IGBT				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
V_{CES}	*collector emitter voltage*		T_{VJ} = 25°C			1200	V
V_{GES}	*max. DC gate voltage*					±20	V
V_{GEM}	*max. transient collector gate voltage*					±30	V
I_{C25}	*collector current*		T_C = 25°C			220	A
I_{C80}			T_C = 80°C			150	A
P_{tot}	*total power dissipation*		T_C = 25°C			695	W
$V_{CE(sat)}$	*collector emitter saturation voltage*	I_C = 150A; V_{GE} = 15 V	T_{VJ} = 25°C		1.8	2.1	V
			T_{VJ} = 125°C		2.1		V
$V_{GE(th)}$	*gate emitter threshold voltage*	I_C = 6 mA; V_{GE} = V_{CE}	T_{VJ} = 25°C	5.4	5.9	6.5	V
I_{CES}	*collector emitter leakage current*	V_{CE} = V_{CES}; V_{GE} = 0 V	T_{VJ} = 25°C			0.1	mA
			T_{VJ} = 125°C		0.1		mA
I_{GES}	*gate emitter leakage current*	V_{GE} = ±20 V				500	nA
$Q_{G(on)}$	*total gate charge*	V_{CE} = 600 V; V_{GE} = 15 V; I_C = 150 A			470		nC
$t_{d(on)}$	*turn-on delay time*				70		ns
t_r	*current rise time*				40		ns
$t_{d(off)}$	*turn-off delay time*	inductive load	T_{VJ} = 125°C		250		ns
t_f	*current fall time*	V_{CE} = 600 V; I_C = 150 A			100		ns
E_{on}	*turn-on energy per pulse*	V_{GE} = ±15 V; R_G = 4.7 Ω			14		mJ
E_{off}	*turn-off energy per pulse*				16		mJ
RBSOA	*reverse bias safe operating area*	V_{GE} = ±15 V; R_G = 4.7 Ω	T_{VJ} = 125°C				
I_{CM}		V_{CEmax} = 1200 V				450	A
SCSOA	*short circuit safe operating area*	V_{CEmax} = 1200 V					
t_{SC}	*short circuit duration*	V_{CE} = 900 V; V_{GE} = ±15 V	T_{VJ} = 125°C			10	µs
I_{SC}	*short circuit current*	R_G = 4.7 Ω; non-repetitive			600		A
R_{thJC}	*thermal resistance junction to case*					0.18	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.2		K/W

Diode							
V_{RRM}	*max. repetitive reverse voltage*		T_{VJ} = 25°C			1200	V
I_{F25}	*forward current*		T_C = 25°C			190	A
I_{F80}			T_C = 80°C			130	A
V_F	*forward voltage*	I_F = 150 A	T_{VJ} = 25°C			2.20	V
			T_{VJ} = 125°C		1.95		V
I_R	*reverse current*	V_R = V_{RRM}	T_{VJ} = 25°C			0.3	mA
			T_{VJ} = 125°C		0.8		mA
Q_{rr}	*reverse recovery charge*				20		µC
I_{RM}	*max. reverse recovery current*	V_R = 600 V			175		A
t_{rr}	*reverse recovery time*	-di_F/dt = 2500 A/µs	T_{VJ} = 125°C		350		ns
E_{rec}	*reverse recovery energy*	I_F = 150 A; V_{GE} = 0 V			10		mJ
R_{thJC}	*thermal resistance junction to case*					0.28	K/W
R_{thCH}	*thermal resistance case to heatsink*				0.2		K/W

tentative

Package V1-A-Pack				Ratings			
Symbol	Definition	Conditions		min.	typ.	max.	Unit
I_{RMS}	*RMS current*	per terminal				100	A
T_{stg}	*storage temperature*			-40		125	°C
T_{VJ}	*virtual junction temperature*			-40		150	°C
Weight					37		g
M_D	*mounting torque*			2		2.5	Nm
V_{ISOL}	*isolation voltage*	t = 1 second	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA	3600			V
		t = 1 minute		3000			V
$d_{Spp/App}$	*creepage distance on surface | striking distance through air*		*terminal to terminal*	6.0			mm
$d_{Spb/Apb}$			*terminal to backside*	12.0			mm

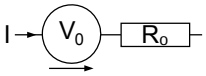


Part number

M = Module
I = IGBT
X = XPT IGBT
A = Gen 1 / std
150 = Current Rating [A]
Q = Buck Chopper
1200 = Reverse Voltage [V]
VA = V1-A-Pack

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MIXA150Q1200VA	MIXA150Q1200VA	Box	10	512328

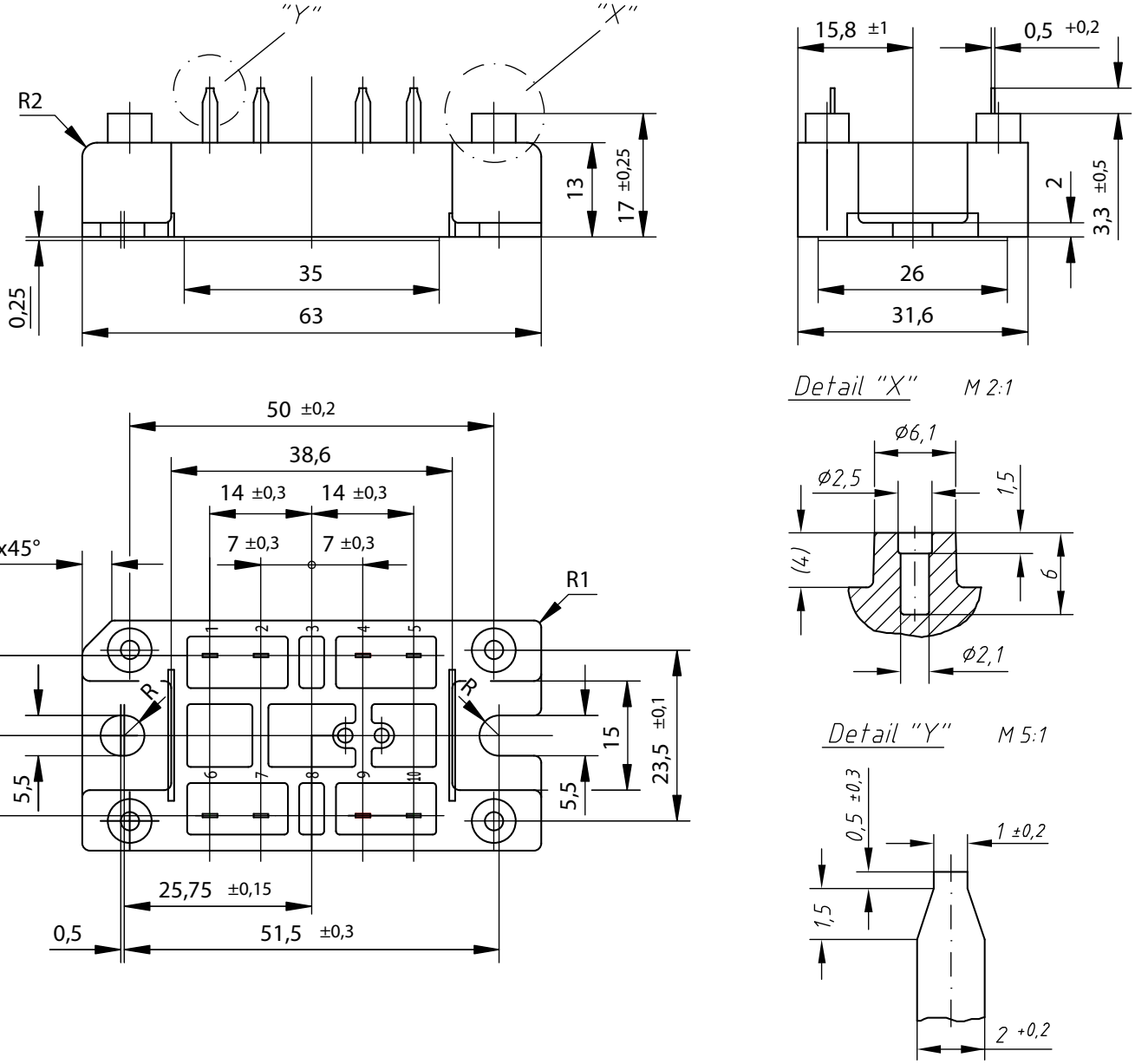
Equivalent Circuits for Simulation ** on die level* T_{VJ} = 150°C

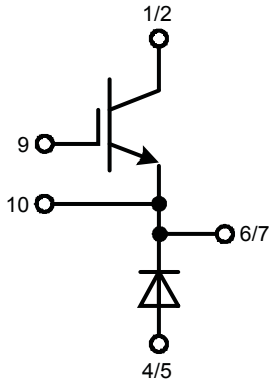


		IGBT	Diode	
$V_{0\,max}$	*threshold voltage*	1.1	1.25	V
$R_{0\,max}$	*slope resistance **	9.2	5.7	mΩ

tentative

Outlines V1-A-Pack





IGBT

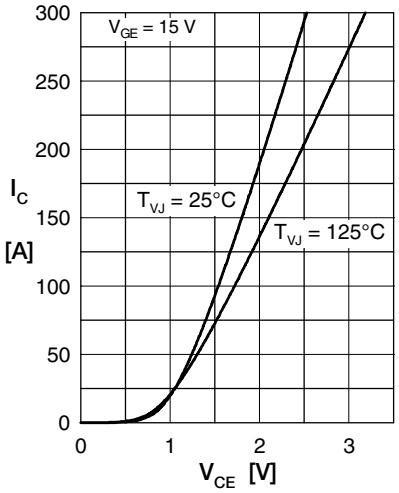


Fig. 1 Typ. output characteristics

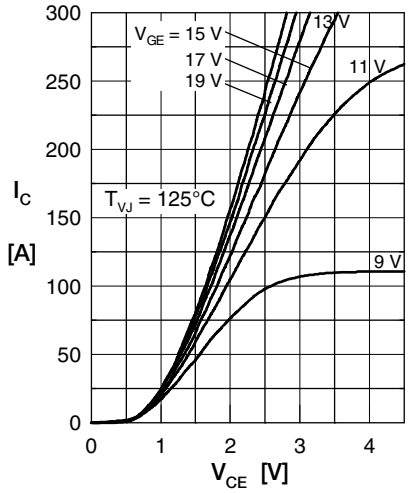


Fig. 2 Typ. output characteristics

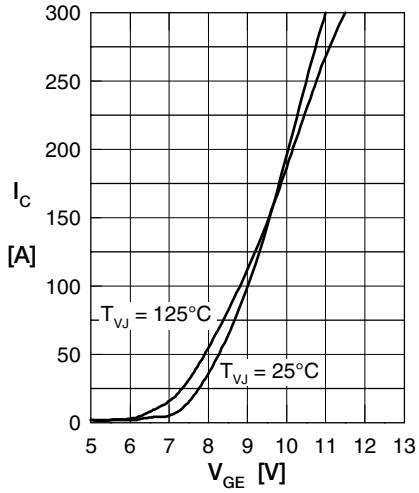


Fig. 3 Typ. tranfer characteristics

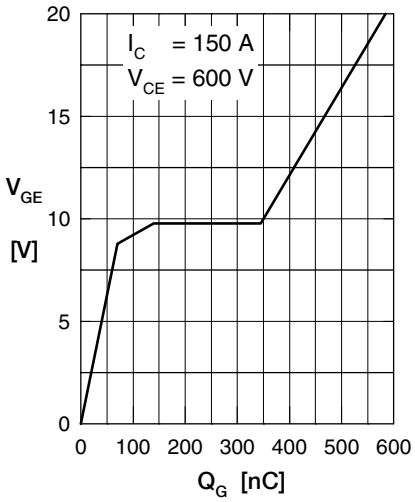


Fig. 4 Typ. turn-on gate charge

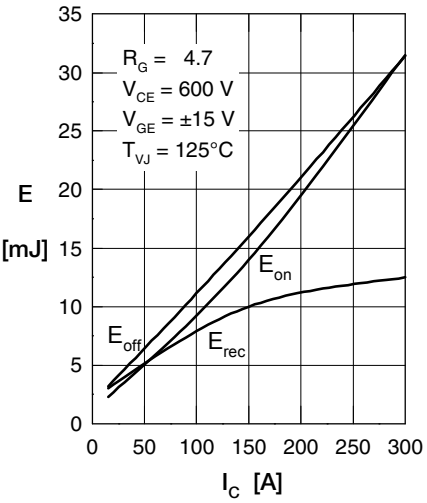


Fig. 5 Typ. switching energy versus collector current

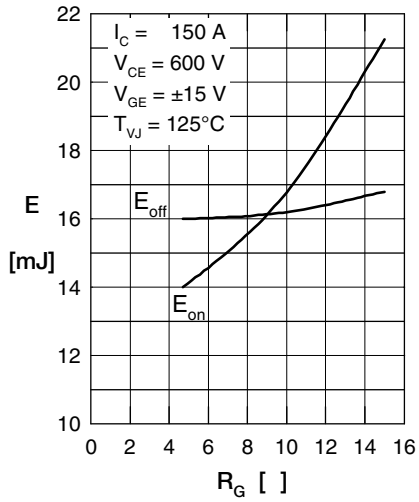


Fig. 6 Typ. switching energy versus gate resistance

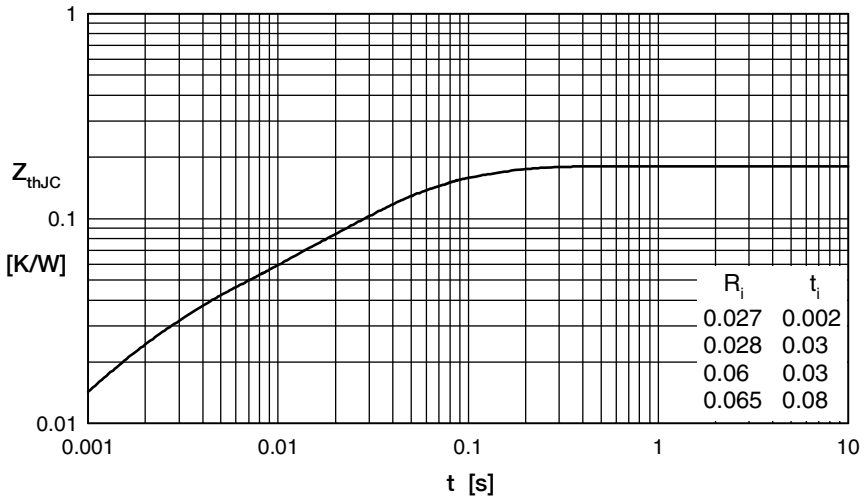


Fig. 7 Typ. transient thermal impedance

Diode

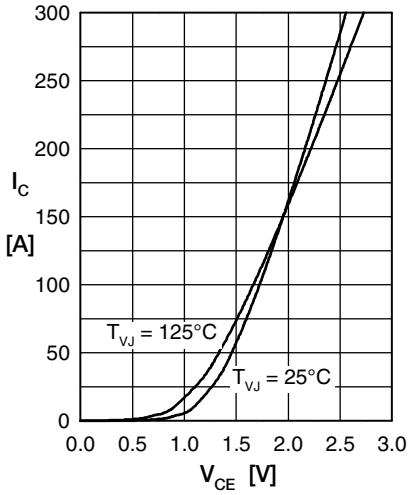


Fig. 1 Typ. Forward current versus V_F

Fig. 2 Typ. reverse recovery charge Q_{rr} versus di/dt

Fig. 3 Typ. peak reverse current I_{RM} versus di/dt

Fig. 4 Dynamic parameters Q_r, I_{RM} versus T_{VJ}

Fig. 5 Typ. recovery time t_{rr} versus $-di_F/dt$

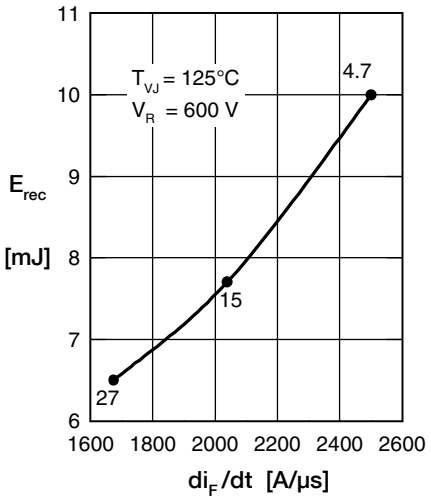


Fig. 6 Typ. recovery energy E_{rec} versus -di/dt

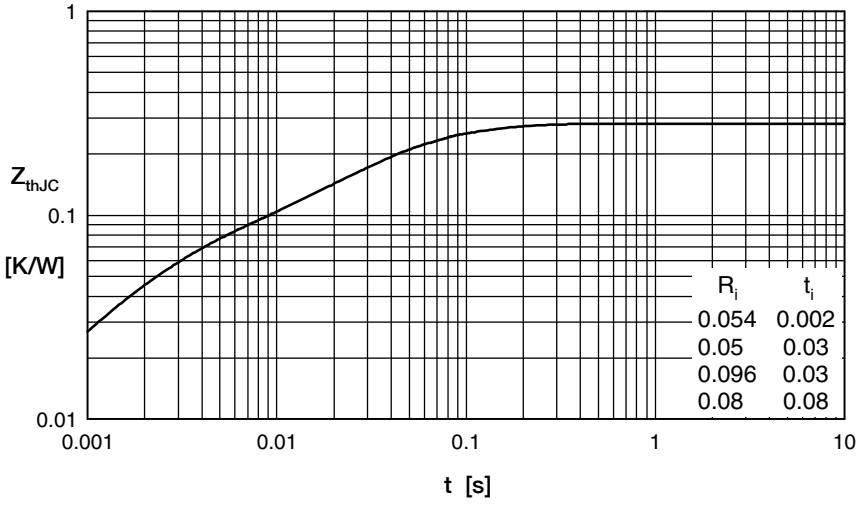


Fig. 7 Transient thermal impedance junction to case